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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10047119	FILING DATE 01/17/2002	CLASS 250	SUBCLASS	GAU 2878	EXAMINER
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****APPLICANTS:** Hong Minghui; Ye Kaidong; An Chengwu; Liu Da Ming;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**
SINGAPORE 200104057-5 07/06/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
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Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 2826-9
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TITLE : Method and apparatus for cutting a multi-layer substrate by dual laser irradiation

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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